

Parker Chomerics CHO-FORM 5531 EMI Shielding Material

Category : Polymer , Thermoset , Rubber or Thermoset Elastomer (TSE) , Silicone

Material Notes:

One component, moisture cure, form-in-place EMI gasketing material. This electrically conductive formulation contains silver-plated copper particles dispersed in a silicone elastomer. It is designed to be robotically dispensed using high pressure dispense equipment. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-FORM-5531-EMI-Shielding-Material.php

Physical Properties	Metric	English	Comments
Specific Gravity	3.20 g/cc	3.20 g/cc	ASTM D792
Deformation	10 %	10 %	4 N/cm
	20 %	20 %	8 N/cm
	30 %	30 %	15 N/cm
	40 %	40 %	28 N/cm
	50 %	50 %	52 N/cm

Mechanical Properties	Metric	English	Comments
Hardness, Shore A	35	35	ASTM D2240
Tensile Strength at Break	>= 0.517 MPa	>= 75.0 psi	ASTM D412
Compression Set	40 %	40 %	ASTM D395 Method B 22 hrs 85°C
	40 % @Temperature 85.0 °C, Time 79200 sec	40 % @Temperature 185 °F, Time 22.0 hour	ASTM D395 Method B

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	85.0 °C	185 °F	

Electrical Properties	Metric	English	Comments
Volume Resistivity	0.0030 ohm-cm	0.0030 ohm-cm	Initial; Chomerics MAT-1002
	0.0040 ohm-cm	0.0040 ohm-cm	Aged; Chomerics MAT-1002
Shielding Effectiveness	52 dB @Frequency 1.00e+10 Hz	52 dB @Frequency 1.00e+10 Hz	CHO-TP08

Electrical Properties	Metric	English	Comments
	@Frequency 2.00e+9 Hz	@Frequency 2.00e+9 Hz	CHO-TP08
	65 dB	65 dB	
	@Frequency 6.00e+9 Hz	@Frequency 6.00e+9 Hz	CHO-TP08
	67 dB	67 dB	
	@Frequency 1.00e+9 Hz	@Frequency 1.00e+9 Hz	CHO-TP08
	71 dB	71 dB	
	@Frequency 2.00e+8 Hz	@Frequency 2.00e+8 Hz	CHO-TP08

Processing Properties	Metric	English	Comments
Extrusion Rate	5.50 g/min	5.50 g/min	
Cure Time	18.0 min	0.300 hour	50% RH; Tack Free Time
	@Temperature 22.0 °C	@Temperature 71.6 °F	
	240 min	4.00 hour	50% RH; Handling Time
	@Temperature 22.0 °C	@Temperature 71.6 °F	
	2880 min	48.0 hour	50% RH; Full Cure
	@Temperature 22.0 °C	@Temperature 71.6 °F	

Descriptive Properties	Value	Comments
Cure Mechanism	Moisture	
Filler	Ag/Cu	
Resin	One Part Silicone	
Time for QC Measurements	8 hrs	Electrical Resistance and Adhesion @ 22°C 50% RH

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